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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	18144
Number of Logic Elements/Cells	-
Total RAM Bits	165888
Number of I/O	516
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax1000-fg896

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

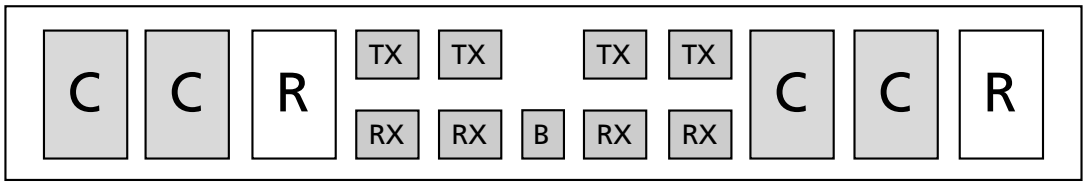


Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

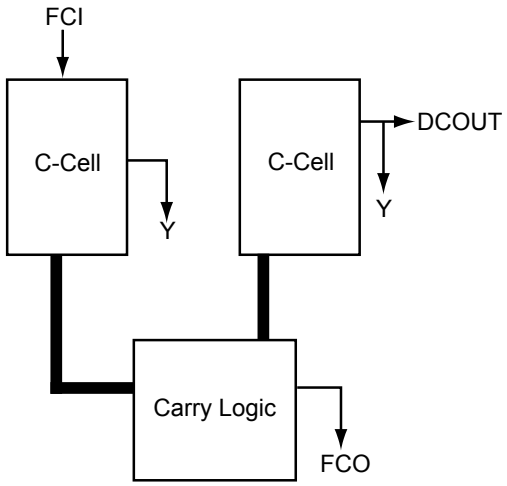


Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • **Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

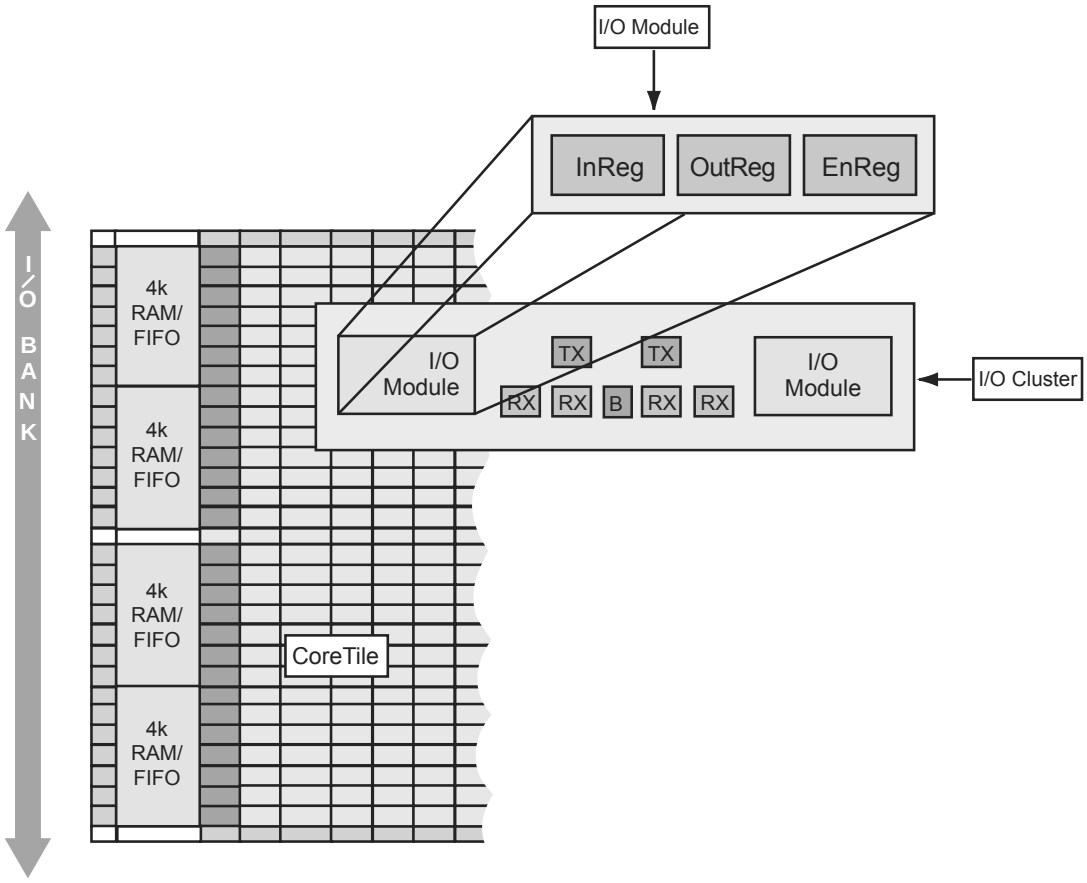


Figure 1-7 • **I/O Cluster Arrangement**

Routing

The AX hierarchical routing structure ties the logic modules, the embedded memory blocks, and the I/O modules together (Figure 1-8 on page 1-6). At the lowest level, in and between SuperClusters, there are three local routing structures: FastConnect, DirectConnect, and CarryConnect routing. DirectConnects provide the highest performance routing inside the SuperClusters by connecting a C-cell to the adjacent R-cell. DirectConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

FastConnects provide high-performance, horizontal routing inside the SuperCluster and vertical routing to the SuperCluster immediately below it. Only one programmable connection is used in a FastConnect path, delivering a maximum routing delay of 0.4 ns.

CarryConnects are used for routing carry logic between adjacent SuperClusters. They connect the FCO output of one two-bit, C-cell carry logic to the FCI input of the two-bit, C-cell carry logic of the SuperCluster below it. CarryConnects do not require an antifuse to make the connection and achieve a signal propagation time of less than 0.1 ns.

The next level contains the core tile routing. Over the SuperClusters within a core tile, both vertical and horizontal tracks run across rows or columns, respectively. At the chip level, vertical and horizontal tracks extend across the full length of the device, both north-to-south and east-to-west. These tracks are composed of highway routing that extend the entire length of the device (segmented at core tile boundaries) as well as segmented routing of varying lengths.

Figure 1-8 • **AX Routing Structures**

Global Resources

Each family member has three types of global signals available to the designer: HCLK, CLK, and GCLR/GPSET. There are four hardwired clocks (HCLK) per device that can directly drive the clock input of each R-cell. Each of the four routed clocks (CLK) can drive the clock, clear, preset, or enable pin of an R-cell or any input of a C-cell (Figure 1-3 on page 1-2).

Global clear (GCLR) and global preset (GPSET) drive the clear and preset inputs of each R-cell as well as each I/O Register on a chip-wide basis at power-up.

Each HCLK and CLK has an associated analog PLL (a total of eight per chip). Each embedded PLL can be used for clock delay minimization, clock delay adjustment, or clock frequency synthesis. The PLL is capable of operating with input frequencies ranging from 14 MHz to 200 MHz and can generate output frequencies between 20 MHz and 1 GHz. The clock can be either divided or multiplied by factors ranging from 1 to 64. Additionally, multiply and divide settings can be used in any combination as long as the resulting clock frequency is between 20 MHz and 1 GHz. Adjacent PLLs can be cascaded to create complex frequency combinations.

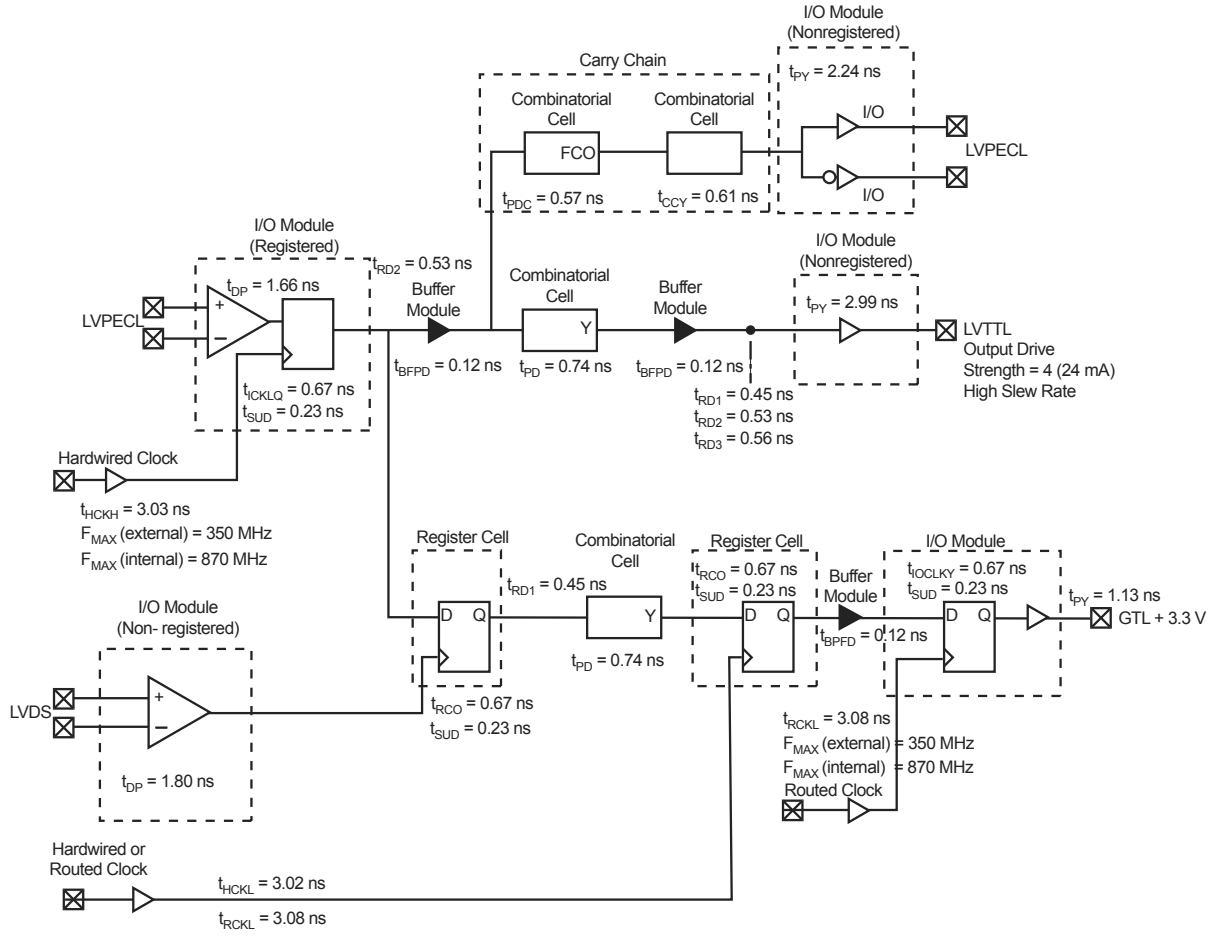
The PLL can be used to introduce either a positive or a negative clock delay of up to 3.75 ns in 250 ps increments. The reference clock required to drive the PLL can be derived from three sources: external input pad (either single-ended or differential), internal logic, or the output of an adjacent PLL.

Low Power (LP) Mode

The AX architecture was created for high-performance designs but also includes a low power mode (activated via the LP pin). When the low power mode is activated, I/O banks can be disabled (inputs disabled, outputs tristated), and PLLs can be placed in a power-down mode. All internal register states are maintained in this mode. Furthermore, individual I/O banks can be configured to opt out of the LP mode, thereby giving the designer access to critical signals while the rest of the chip is in low power mode.

The power can be further reduced by providing an external voltage source (V_{PUMP}) to the device to bypass the internal charge pump (See "Low Power Mode" on page 2-106 for more information).

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{HCKL}$

$= (1.72 + 0.53 + 0.23) – 3.02 = –0.54$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.02 + 0.67 + 0.45 + 2.99 = 7.13$ ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{RCKH}$

$= (1.72 + 0.53 + 0.23) – 3.13 = –0.65$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.13 + 0.67 + 0.45 + 3.03 = 7.24$ ns

Table 2-15, Table 2-16, and Table 2-17 list all the available macro names differentiated by I/O standard, type, slew rate, and drive strength.

***Table 2-15* • Macros for Single-Ended I/O Standards**

Standard	VCCI	Macro Names
LVTTL	3.3 V	CLKBUF, HCLKBUF INBUF, OUTBUF, OUTBUF_S_8, OUTBUF_S_12, OUTBUF_S_16, OUTBUF_S_24, OUTBUF_H_8, OUTBUF_H_12, OUTBUF_H_16, OUTBUF_H_24, TRIBUF, TRIBUF_S_8, TRIBUF_S_12, TRIBUF_S_16, TRIBUF_S_24, TRIBUF_H_8, TRIBUF_H_12, TRIBUF_H_16, TRIBUF_H_24, BIBUF, BIBUF_S_8, BIBUF_S_12, BIBUF_S_16, BIBUF_S_24, BIBUF_H_8, BIBUF_H_12, BIBUF_H_16, BIBUF_H_24
3.3 V PCI	3.3 V	CLKBUF_PCI, HCLKBUF_PCI, INBUF_PCI, OUTBUF_PCI, TRIBUF_PCI, BIBUF_PCI
3.3 V PCI-X	3.3 V	CLKBUF_PCI-X, HCLKBUF_PCI-X, INBUF_PCI-X, OUTBUF_PCI-X, TRIBUF_PCI-X, BIBUF_PCI-X
LVCMOS25	2.5 V	CLKBUF_LVCMOS25, HCLKBUF_LVCMOS25, INBUF_LVCMOS25, OUTBUF_LVCMOS25, TRIBUF_LVCMOS25, BIBUF_LVCMOS25
LVCMOS18	1.8 V	CLKBUF_LVCMOS18, HCLKBUF_LVCMOS18, INBUF_LVCMOS18, OUTBUF_LVCMOS18, TRIBUF_LVCMOS18, BIBUF_LVCMOS18
LVCMOS15 (JESD8-11)	1.5 V	CLKBUF_LVCMOS15, HCLKBUF_LVCMOS15, INBUF_LVCMOS15, OUTBUF_LVCMOS15, TRIBUF_LVCMOS15, BIBUF_LVCMOS15

***Table 2-16* • I/O Macros for Differential I/O Standards**

Standard	VCCI	Macro Names
LVPECL	3.3 V	CLKBUF_LVPECL, HCLKBUF_LVPECL, INBUF_LVPECL, OUTBUF_LVPECL
LVDS	2.5 V	CLKBUF_LVDS, HCLKBUF_LVDS, INBUF_LVDS, OUTBUF_LVDS

***Table 2-17* • I/O Macros for Voltage-Referenced I/O Standards**

Standard	VCCI	VREF	Macro Names
GTL+	3.3 V	1.0 V	CLKBUF_GTP33, HCLKBUF_GTP33, INBUF_GTP33, OUTBUF_GTP33, TRIBUF_GTP33, BIBUF_GTP33
GTL+	2.5 V	1.0 V	CLKBUF_GTP25, HCLKBUF_GTP25, INBUF_GTP25, OUTBUF_GTP25, TRIBUF_GTP25, BIBUF_GTP25
SSTL2 Class I	2.5 V	1.25 V	CLKBUF_SSTL2_I, HCLKBUF_SSTL2_I, INBUF_SSTL2_I, OUTBUF_SSTL2_I, TRIBUF_SSTL2_I, BIBUF_SSTL2_I
SSTL2 Class II	2.5 V	1.25 V	CLKBUF_SSTL2_II, HCLKBUF_SSTL2_II, INBUF_SSTL2_II, OUTBUF_SSTL2_II, TRIBUF_SSTL2_II, BIBUF_SSTL2_II
SSTL3 Class I	3.3 V	1.5 V	CLKBUF_SSTL3_I, HCLKBUF_SSTL3_I, INBUF_SSTL3_I, OUTBUF_SSTL3_I, TRIBUF_SSTL3_I, BIBUF_SSTL3_I
SSTL3 Class II	3.3 V	1.5 V	CLKBUF_SSTL3_II, HCLKBUF_SSTL3_II, INBUF_SSTL3_II, OUTBUF_SSTL3_II, TRIBUF_SSTL3_II, BIBUF_SSTL3_II
HSTL Class I	1.5 V	0.75 V	CLKBUF_HSTL_I, HCLKBUF_HSTL_I, INBUF_HSTL_I, OUTBUF_HSTL_I, TRIBUF_HSTL_I, BIBUF_HSTL_I

***Table 2-36* • 3.3 V PCI-X I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
3.3 V PCI-X Output Module Timing								
t_{DP}	Input Buffer		1.57		1.79		2.10	ns
t_{PY}	Output Buffer		2.10		2.40		2.82	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		1.61		1.62		1.63	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		1.59		1.60		1.61	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		2.65		3.02		3.55	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		3.11		3.55		4.17	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

PLLRCLK and PLLHCLK

PLLRCLK (PLLHCLK) is used to drive global resource CLK (HCLK) from a PLL (Figure 2-44).

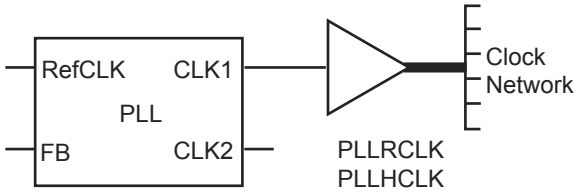


Figure 2-44 • **PLLRCLK and PLLHCLK**

Using Global Resources with PLLs

Each global resource has an associated PLL at its root. For example, PLLA can drive HCLKA, PLLE can drive CLKE, etc. (Figure 2-45).

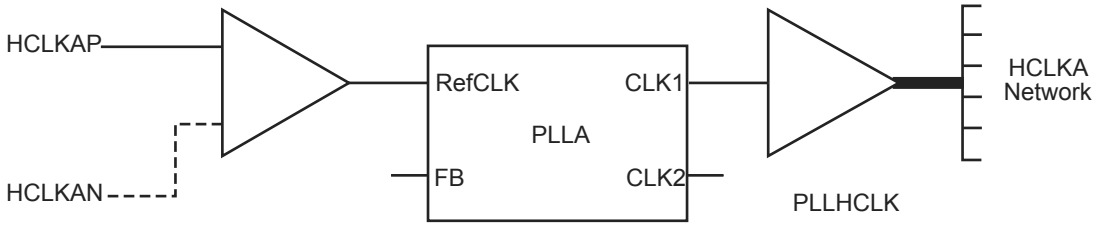


Figure 2-45 • **Example of HCLKA Driven from a PLL with External Clock Source**

In addition, each clock pin of the package can be used to drive either its associated global resource or PLL. For example, package pins CLKEP and CLKEN can drive either the RefCLK input of PLLE or CLKE.

There are two macros required when interfacing the embedded PLLs with the global resources: PLLINT and PLLOUT.

PLLINT

This macro is used to drive the RefCLK input of the PLL internally from user signals.

PLLOUT

This macro is used to connect either the CLK1 or CLK2 output of a PLL to the regular routing network (Figure 2-46).

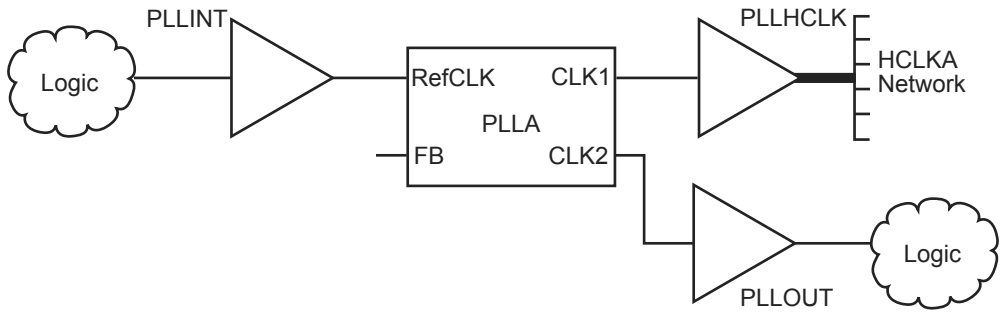


Figure 2-46 • **Example of PLLINT and PLLOUT Usage**

Axcelerator Clock Management System

Introduction

Each member of the Axcelerator family[6] contains eight phase-locked loop (PLL) blocks which perform the following functions:

- Programmable Delay (32 steps of 250 ps)
- Clock Skew Minimization
- Clock Frequency Synthesis

Each PLL has the following key features:

- Input Frequency Range – 14 to 200 MHz
- Output Frequency Range – 20 MHz to 1 GHz
- Output Duty Cycle Range – 45% to 55%
- Maximum Long-Term Jitter – 1% or 100ps (whichever is greater)
- Maximum Short-Term Jitter – 50ps + 1% of Output Frequency
- Maximum Acquisition Time (lock) – 20µs

Physical Implementation

The eight PLL blocks are arranged in two groups of four. One group is located in the center of the northern edge of the chip, while the second group is centered on the southern edge. The northern group is associated with the four HCLK networks (e.g. PLLA can drive HCLKA), while the southern group is associated with the four CLK networks (e.g. PLLE can drive CLKE).

Each PLL cell is connected to two I/O pads and a PLL Cluster that interfaces with the FPGA core. Figure 2-48 illustrates a PLL block. The VCCPLL pin should be connected to a 1.5V power supply through a 250 Ω resistor. Furthermore, 0.1 µF and 10 µF decoupling capacitors should be connected across the VCCPLL and VCOMPPLL pins.

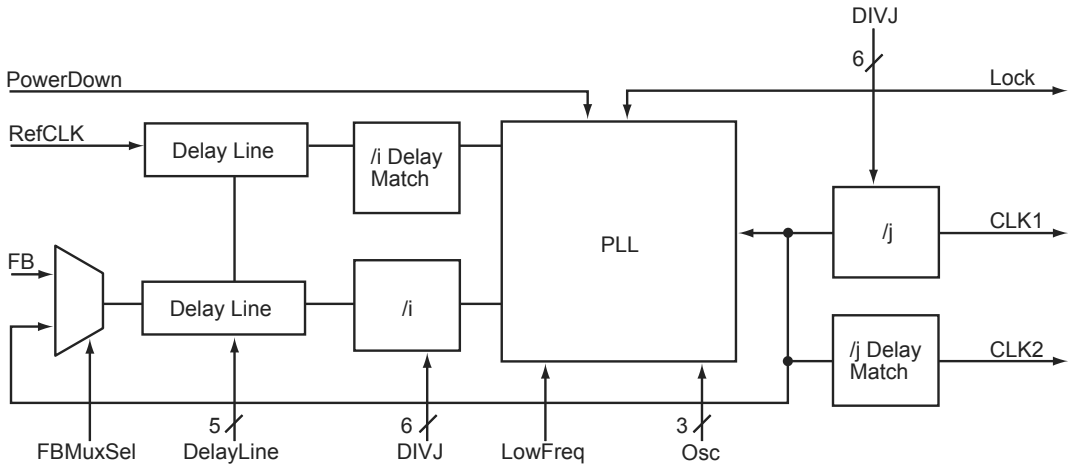


Figure 2-48 • **PLL Block Diagram**

Note: The VCOMPPLL pin should never be grounded (Figure 2-2 on page 2-9)!

The I/O pads associated with the PLL can also be configured for regular I/O functions except when it is used as a clock buffer. The I/O pads can be configured in all the modes available to the regular I/O pads in the same I/O bank. In particular, the [H]CLKxP pad can be configured as a differential pair,

6. *AX2000-CQ256 does not support operation of the phase-locked loops. This is in order to support full pin compatibility with RTAX2000S/SL-CQ256.*

Timing Characteristics

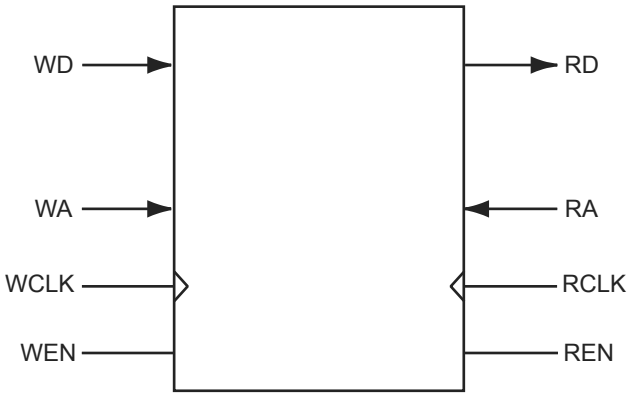


Figure 2-58 • **SRAM Model**

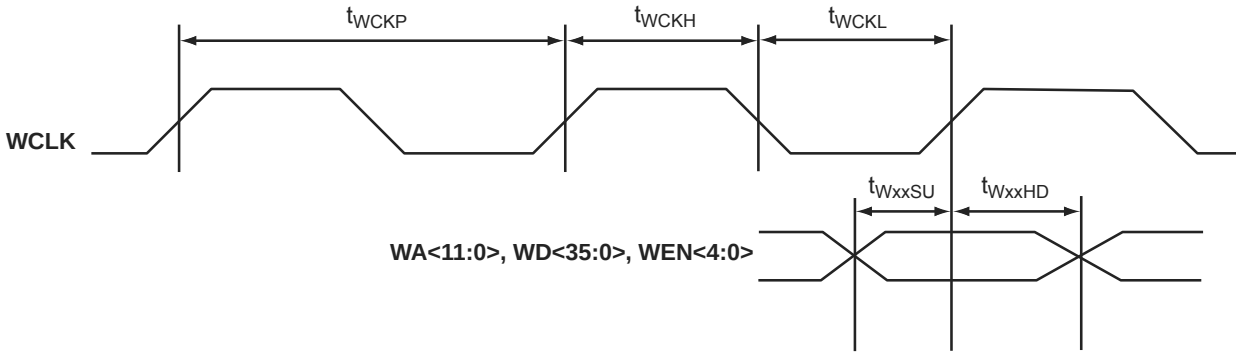


Figure 2-59 • **RAM Write Timing Waveforms**

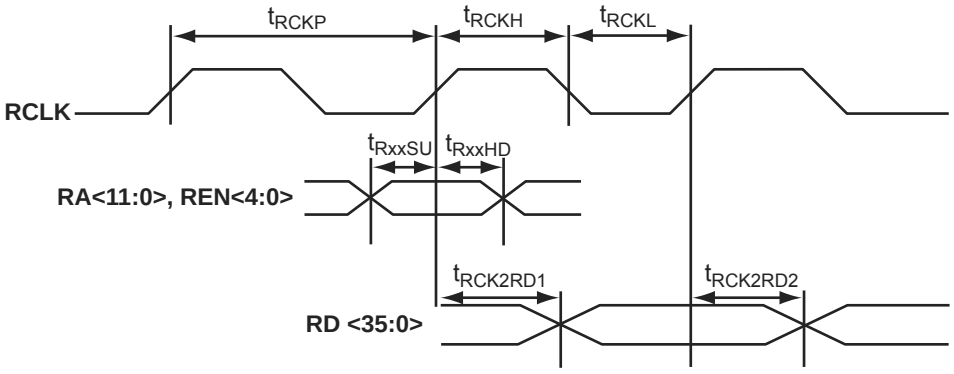


Figure 2-60 • **RAM Read Timing Waveforms**

BG729	
AX1000 Function	Pin Number
IO218PB6F20	V2
IO219NB6F20	T1
IO219PB6F20	U1
IO220NB6F20	R5
IO220PB6F20	R6
IO221NB6F20	T3
IO221PB6F20	T4
IO222NB6F20	R2
IO222PB6F20	T2
IO223NB6F20	P8
IO223PB6F20	P9
IO224NB6F20	R3
IO224PB6F20	R4
Bank 7	
IO225NB7F21	P1
IO225PB7F21	R1
IO226NB7F21	P3
IO226PB7F21	P2
IO227NB7F21	N7
IO227PB7F21	P7
IO228NB7F21	P5
IO228PB7F21	P4
IO229NB7F21	N2
IO229PB7F21	N1
IO230NB7F21	N6
IO230PB7F21	P6
IO231NB7F21	N9
IO231PB7F21	N8
IO232NB7F21	N4
IO232PB7F21	N3
IO233NB7F21	M2
IO233PB7F21	M1
IO234NB7F21	M4
IO234PB7F21	M3
IO235NB7F21	M5
IO235PB7F21	N5
IO236NB7F22	L2

BG729	
AX1000 Function	Pin Number
IO236PB7F22	L1
IO237NB7F22	L4
IO237PB7F22	L3
IO238NB7F22	L6
IO238PB7F22	M6
IO239NB7F22	M8
IO239PB7F22	M7
IO240NB7F22	K2
IO240PB7F22	K1
IO241NB7F22	K4
IO241PB7F22	K3
IO242NB7F22	K5
IO242PB7F22	L5
IO243NB7F22	J2
IO243PB7F22	J1
IO244NB7F22	J4
IO244PB7F22	J3
IO245NB7F22	H2
IO245PB7F22	H1
IO246NB7F22	H4
IO246PB7F22	H3
IO247NB7F23	L8
IO247PB7F23	L7
IO248NB7F23	J6
IO248PB7F23	K6
IO249NB7F23	H5
IO249PB7F23	J5
IO250NB7F23	G2
IO250PB7F23	G1
IO251NB7F23	K8
IO251PB7F23	K7
IO252NB7F23	G4
IO252PB7F23	G3
IO253NB7F23	F2
IO253PB7F23	F1
IO254NB7F23	G6
IO254PB7F23	H6

BG729	
AX1000 Function	Pin Number
IO255NB7F23	F5
IO255PB7F23	G5
IO256NB7F23	F3
IO256PB7F23	F4
IO257NB7F23	H7
IO257PB7F23	J7
Dedicated I/O	
GND	A1
GND	A2
GND	A25
GND	A26
GND	A27
GND	A3
GND	AC24
GND	AE1
GND	AE2
GND	AE25
GND	AE26
GND	AE27
GND	AE3
GND	AE5
GND	AF1
GND	AF2
GND	AF25
GND	AF26
GND	AF27
GND	AF3
GND	AG1
GND	AG2
GND	AG25
GND	AG26
GND	AG27
GND	AG3
GND	B1
GND	B2
GND	B25
GND	B26

BG729	
AX1000 Function	**Pin Number**
VCCIB0	B4
VCCIB0	C4
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K12
VCCIB0	K13
VCCIB1	A24
VCCIB1	B24
VCCIB1	C24
VCCIB1	J16
VCCIB1	J17
VCCIB1	J18
VCCIB1	K15
VCCIB1	K16
VCCIB2	D25
VCCIB2	D26
VCCIB2	D27
VCCIB2	K19
VCCIB2	L19
VCCIB2	M18
VCCIB2	M19
VCCIB2	N18
VCCIB3	AD25
VCCIB3	AD26
VCCIB3	AD27
VCCIB3	R18
VCCIB3	T18
VCCIB3	T19
VCCIB3	U19
VCCIB3	V19
VCCIB4	AE24
VCCIB4	AF24
VCCIB4	AG24
VCCIB4	V15
VCCIB4	V16
VCCIB4	W16

BG729	
AX1000 Function	**Pin Number**
VCCIB4	W17
VCCIB4	W18
VCCIB5	AE4
VCCIB5	AF4
VCCIB5	AG4
VCCIB5	V12
VCCIB5	V13
VCCIB5	W10
VCCIB5	W11
VCCIB5	W12
VCCIB6	AD1
VCCIB6	AD2
VCCIB6	AD3
VCCIB6	R10
VCCIB6	T10
VCCIB6	T9
VCCIB6	U9
VCCIB6	V9
VCCIB7	D1
VCCIB7	D2
VCCIB7	D3
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCOMPLA	B13
VCOMPLB	A14
VCOMPLC	A15
VCOMPLD	J15
VCOMPLE	AG15
VCOMPLF	W15
VCOMPLG	AC14
VCOMPLH	W13
VPUMP	D24

FG484	
AX1000 Function	**Pin Number**
IO246NB7F22	F3
IO246PB7F22	G3
IO250NB7F23	F4
IO250PB7F23	G4
IO253NB7F23	G5
IO253PB7F23	G6
IO254NB7F23	D1
IO254PB7F23	E1
IO257NB7F23	F5
IO257PB7F23	E4
Dedicated I/O	
VCCDA	H7
GND	A1
GND	A11
GND	A12
GND	A2
GND	A21
GND	A22
GND	AA1
GND	AA2
GND	AA21
GND	AA22
GND	AB1
GND	AB11
GND	AB12
GND	AB2
GND	AB21
GND	AB22
GND	B1
GND	B2
GND	B21
GND	B22
GND	C20
GND	C3
GND	D19

FG484	
AX1000 Function	**Pin Number**
GND	D4
GND	E18
GND	E5
GND	G18
GND	H15
GND	H8
GND	J14
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	L1
GND	L10
GND	L11
GND	L12
GND	L13
GND	L22
GND	M1
GND	M10
GND	M11
GND	M12
GND	M13
GND	M22
GND	N10
GND	N11
GND	N12
GND	N13
GND	P14
GND	P9
GND	R15
GND	R8
GND	U16
GND	U6
GND	V18

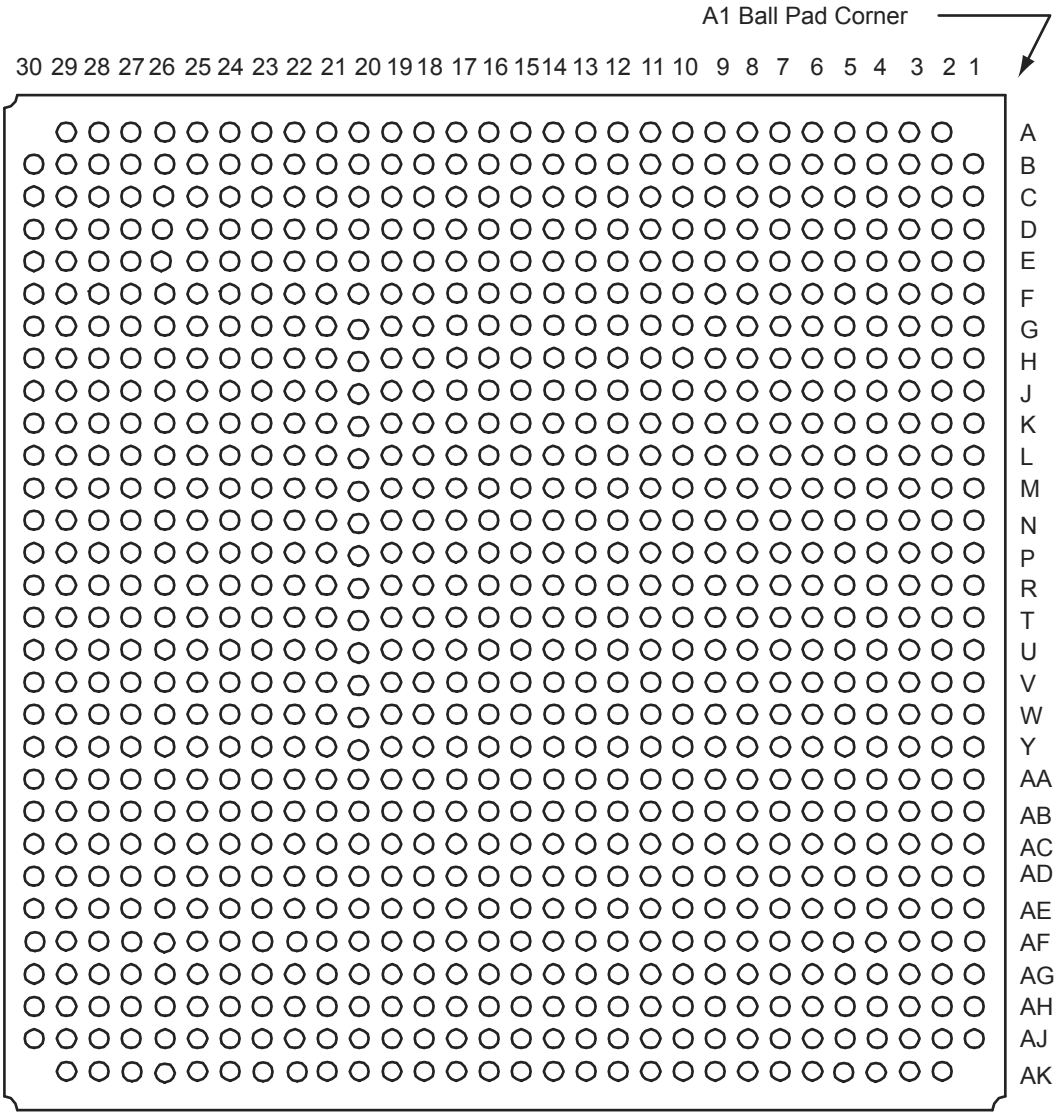
FG484	
AX1000 Function	**Pin Number**
GND	V5
GND	W19
GND	W4
GND	Y20
GND	Y3
GND/LP	G7
PRA	G11
PRB	F11
PRC	T12
PRD	U12
TCK	G8
TDI	F9
TDO	F7
TMS	F6
TRST	F8
VCCA	G17
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J7
VCCA	K14
VCCA	K9
VCCA	L14
VCCA	L9
VCCA	M14
VCCA	M9
VCCA	N14
VCCA	N9
VCCA	P10
VCCA	P11
VCCA	P12
VCCA	P13
VCCA	T6
VCCA	U17

FG484	
AX1000 Function	**Pin Number**
VCCPLA	F10
VCCPLB	G9
VCCPLC	D13
VCCPLD	G13
VCCPLE	U13
VCCPLF	T14
VCCPLG	W10
VCCPLH	T10
VCCDA	AB16
VCCDA	AB8
VCCDA	C10
VCCDA	C11
VCCDA	C14
VCCDA	D14
VCCDA	D5
VCCDA	F16
VCCDA	G12
VCCDA	L4
VCCDA	M18
VCCDA	T11
VCCDA	T17
VCCDA	U7
VCCDA	V14
VCCDA	V8
VCCIB0	A3
VCCIB0	B3
VCCIB0	H10
VCCIB0	H11
VCCIB0	H9
VCCIB1	A20
VCCIB1	B20
VCCIB1	H12
VCCIB1	H13
VCCIB1	H14
VCCIB2	C21

FG484	
AX1000 Function	**Pin Number**
VCCIB2	C22
VCCIB2	J15
VCCIB2	K15
VCCIB2	L15
VCCIB3	M15
VCCIB3	N15
VCCIB3	P15
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA20
VCCIB4	AB20
VCCIB4	R12
VCCIB4	R13
VCCIB4	R14
VCCIB5	AA3
VCCIB5	AB3
VCCIB5	R10
VCCIB5	R11
VCCIB5	R9
VCCIB6	M8
VCCIB6	N8
VCCIB6	P8
VCCIB6	Y1
VCCIB6	Y2
VCCIB7	C1
VCCIB7	C2
VCCIB7	J8
VCCIB7	K8
VCCIB7	L8
VCOMPLA	D10
VCOMPLB	G10
VCOMPLC	E12
VCOMPLD	G14
VCOMPLE	W13
VCOMPLF	T13

FG484	
AX1000 Function	**Pin Number**
VCOMPLG	V11
VCOMPLH	T9
VPUMP	D17

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG1152	
AX2000 Function	Pin Number
IO51PB1F4	J20
IO52NB1F4	B20
IO52PB1F4	A20
IO53NB1F4	F20
IO53PB1F4	E20
IO54NB1F5	B21
IO54PB1F5	A21
IO55NB1F5	K21
IO55PB1F5	J21
IO56NB1F5	D21
IO56PB1F5	C21
IO57NB1F5	G22
IO57PB1F5	G21
IO58NB1F5	E22
IO58PB1F5	E21
IO59NB1F5	D22
IO59PB1F5	C22
IO60NB1F5	B23
IO60PB1F5	A23
IO61NB1F5	H22
IO61PB1F5	H21
IO62NB1F5	C24
IO62PB1F5	C23
IO63NB1F5	F23
IO63PB1F5	F22
IO64NB1F6	B24
IO64PB1F6	A24
IO65NB1F6	J22
IO65PB1F6	K22
IO66NB1F6	B25
IO66PB1F6	A25
IO67NB1F6	K23
IO67PB1F6	J23
IO68NB1F6	F24
IO68PB1F6	E24

FG1152	
AX2000 Function	Pin Number
IO69NB1F6	C27
IO69PB1F6	C26
IO70NB1F6	H24
IO70PB1F6	G24
IO71NB1F6	H23
IO71PB1F6	G23
IO72NB1F6	B28
IO72PB1F6	A28
IO73NB1F6	E26
IO73PB1F6	E25
IO74NB1F6	F26
IO74PB1F6	F25
IO75NB1F6	K25
IO75PB1F6	K24
IO76NB1F7	D27
IO76PB1F7	D26
IO77NB1F7	B29
IO77PB1F7	A29
IO78NB1F7	D28
IO78PB1F7	C28
IO79NB1F7	H25
IO79PB1F7	G25
IO80NB1F7	F27
IO80PB1F7	E27
IO81NB1F7	J25
IO81PB1F7	J24
IO82NB1F7	D29
IO82PB1F7	C29
IO83NB1F7	H26
IO83PB1F7	G26
IO84NB1F7	F28
IO84PB1F7	E28
IO85NB1F7	H27
IO85PB1F7	G27
Bank 2	

FG1152	
AX2000 Function	Pin Number
IO86NB2F8	J28
IO86PB2F8	J27
IO87NB2F8	M25
IO87PB2F8	L25
IO88NB2F8	L26
IO88PB2F8	K26
IO89NB2F8	G31
IO89PB2F8	F31
IO90NB2F8	H29
IO90PB2F8	G29
IO91NB2F8	K28
IO91PB2F8	K27
IO92NB2F8	J30
IO92PB2F8	H30
IO93NB2F8	L28
IO93PB2F8	L27
IO94NB2F8	K29
IO94PB2F8	J29
IO95NB2F8	K31
IO95PB2F8	J31
IO96NB2F9	J32
IO96PB2F9	H32
IO97NB2F9	M27
IO97PB2F9	M26
IO98NB2F9	L30
IO98PB2F9	K30
IO99NB2F9	N25
IO99PB2F9	N26
IO100NB2F9	M29
IO100PB2F9	L29
IO101NB2F9	L33
IO101PB2F9	L32
IO102NB2F9	K34
IO102PB2F9	K33
IO103NB2F9	N28

PQ208	
AX500 Function	**Pin Number**
IO150PB7F14	19
IO152NB7F14	16
IO152PB7F14	17
IO161NB7F15	12
IO161PB7F15	13
IO163NB7F15	10
IO163PB7F15	11
IO165PB7F15	7
IO166NB7F15	5
IO166PB7F15	6
IO167NB7F15	3
IO167PB7F15	4
Dedicated I/O	
V_{CCDA}	1
V_{CCDA}	26
V_{CCDA}	53
V_{CCDA}	63
V_{CCDA}	78
V_{CCDA}	95
V_{CCDA}	105
V_{CCDA}	130
V_{CCDA}	157
V_{CCDA}	167
V_{CCDA}	182
V_{CCDA}	202
GND	104
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90

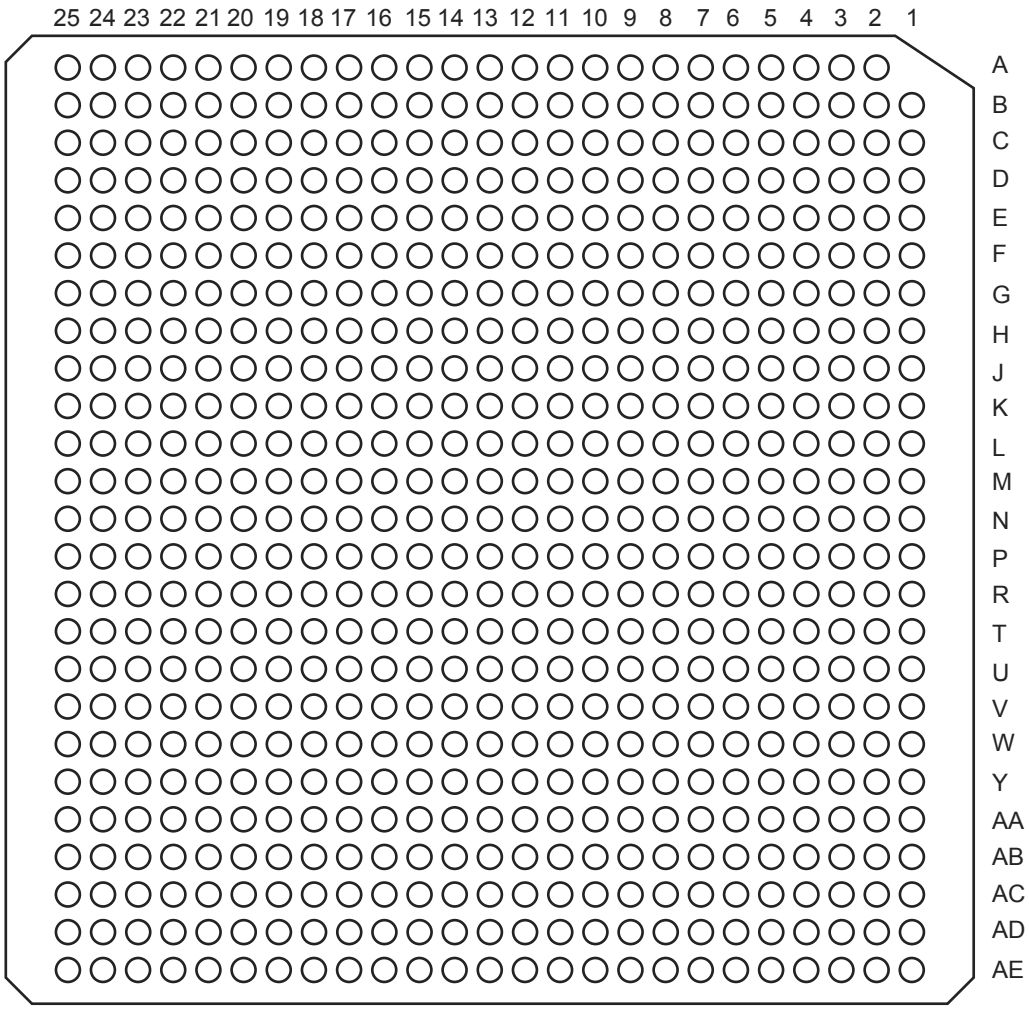
PQ208	
AX500 Function	**Pin Number**
GND	94
GND	99
GND	113
GND	119
GND	125
GND	143
GND	136
GND	150
GND	155
GND	164
GND	169
GND	173
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	14
VCCA	38
VCCA	52
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	156
VCCA	168
VCCA	195
VCCPLA	189

PQ208	
AX500 Function	**Pin Number**
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCCIB0	200
VCCIB0	193
VCCIB1	172
VCCIB1	163
VCCIB2	149
VCCIB2	135
VCCIB3	124
VCCIB3	112
VCCIB4	98
VCCIB4	89
VCCIB5	68
VCCIB5	58
VCCIB6	45
VCCIB6	31
VCCIB7	20
VCCIB7	8
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CQ352	
AX2000 Function	**Pin Number**
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX2000 Function	**Pin Number**
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CG624



Note

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CG624	
AX1000 Function	**Pin Number**
VCCA	U17
VCCA	U9
VCCA	Y4
VCCDA	A12
VCCDA	AA13
VCCDA	AA15
VCCDA	AA7
VCCDA	AC11
VCCDA	AD11
VCCDA	AE17
VCCDA	B15
VCCDA	C15
VCCDA	C6
VCCDA	D13
VCCDA	E13
VCCDA	E19
VCCDA	G5
VCCDA	N21
VCCDA	N5
VCCDA	W21
VCCIB0	A3
VCCIB0	B3
VCCIB0	C4
VCCIB0	D5
VCCIB0	J10
VCCIB0	J11
VCCIB0	K12
VCCIB1	A23
VCCIB1	B23
VCCIB1	C22
VCCIB1	D21
VCCIB1	J15
VCCIB1	J16
VCCIB1	K14
VCCIB2	C24
VCCIB2	C25

CG624	
AX1000 Function	**Pin Number**
VCCIB2	D23
VCCIB2	E22
VCCIB2	K17
VCCIB2	L17
VCCIB2	M16
VCCIB3	AA22
VCCIB3	AB23
VCCIB3	AC24
VCCIB3	AC25
VCCIB3	P16
VCCIB3	R17
VCCIB3	T17
VCCIB4	AB21
VCCIB4	AC22
VCCIB4	AD23
VCCIB4	AE23
VCCIB4	T14
VCCIB4	U15
VCCIB4	U16
VCCIB5	AB5
VCCIB5	AC4
VCCIB5	AD3
VCCIB5	AE3
VCCIB5	T12
VCCIB5	U10
VCCIB5	U11
VCCIB6	AA4
VCCIB6	AB3
VCCIB6	AC1
VCCIB6	AC2
VCCIB6	P10
VCCIB6	R9
VCCIB6	T9
VCCIB7	C1
VCCIB7	C2
VCCIB7	D3

CG624	
AX1000 Function	**Pin Number**
VCCIB7	E4
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCPLA	E12
VCCPLB	J12
VCCPLC	E14
VCCPLD	H14
VCCPLE	Y14
VCCPLF	U14
VCCPLG	Y12
VCCPLH	U12
VCOMPLA	F12
VCOMPLB	H12
VCOMPLC	F14
VCOMPLD	J14
VCOMPLE	AA14
VCOMPLF	V14
VCOMPLG	AA12
VCOMPLH	V12
VPUMP	E20

Revision	Changes	Page
Revision 3 (continued)	The timing characteristics tables from pages 2-26 to 2-60 were updated.	2-26 to 2-60
	The "Global Resources" section was updated.	2-66
	The timing characteristics tables from pages 2-102 to 2-103 were updated.	2-102 to 2-103
	The "PQ208", "FG256", and "FG324" tables are new.	3-9,3-16, 3-84